

## Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

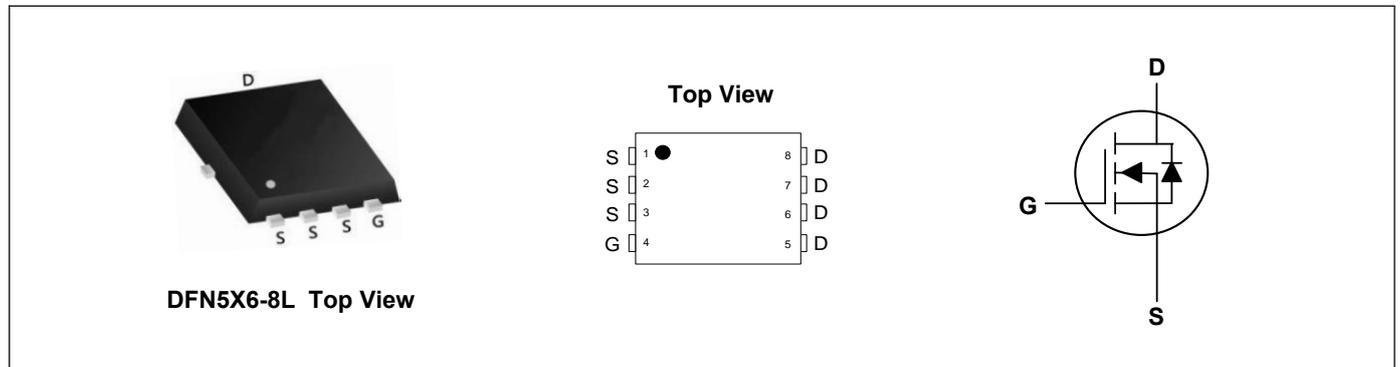
## Applications

- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System
- LCD/LED Back Light

## Product Summary



$V_{DS}$	100	V
$I_D$	34	A
$R_{DS(ON)}$ (at $V_{GS}=10V$ )	11.5	m $\Omega$
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ )	15	m $\Omega$



## Absolute Maximum Ratings( $T_C=25^\circ C$ , unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, $V_{GS}$ @ 10V <sup>1</sup>	$I_D@T_C=25^\circ C$	34	A
Continuous Drain Current, $V_{GS}$ @ 10V <sup>1</sup>	$I_D@T_C=100^\circ C$	31	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	120	A
Single Pulse Avalanche Energy <sup>3</sup>	EAS	33	mJ
Avalanche Current	$I_{AS}$	15	A
Total Power Dissipation <sup>4</sup>	$P_D@T_C=25^\circ C$	56.5	W
Storage Temperature Range	$T_{STG}$	-55 to 150	$^\circ C$
Operating Junction Temperature Range	$T_J$	-55 to 150	$^\circ C$

## Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	---	50	$^\circ C/W$
Thermal Resistance Junction-Case <sup>1</sup>	$R_{\theta JC}$	---	2.2	$^\circ C/W$

**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	100	---	---	V
Static Drain-Source On-Resistance <sup>2</sup>	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	---	8	11.5	m $\Omega$
		$V_{GS}=4.5V, I_D=10A$	---	11.6	15	m $\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	---	2.4	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=80V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	---	---	1	uA
		$V_{DS}=80V, V_{GS}=0V, T_J=55^{\circ}\text{C}$	---	---	5	
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
Total Gate Charge (10V)	$Q_g$	$V_{DS}=50V, V_{GS}=10V, I_D=20A$	---	43	---	nC
Total Gate Charge (4.5V)	$Q_g$		---	18.5	---	
Gate-Source Charge	$Q_{gs}$		---	8.5	---	
Gate-Drain Charge	$Q_{gd}$		---	10.3	---	
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=50V, V_{GS}=10V, R_G=3.3\Omega, I_D=20A$	---	10	---	ns
Rise Time	$T_r$		---	7	---	
Turn-Off Delay Time	$T_{d(off)}$		---	50	---	
Fall Time	$T_f$		---	11	---	
Input Capacitance	$C_{iss}$	$V_{DS}=50V, V_{GS}=0V, f=1\text{MHz}$	---	3150	---	pF
Output Capacitance	$C_{oss}$		---	695	---	
Reverse Transfer Capacitance	$C_{rss}$		---	25	---	

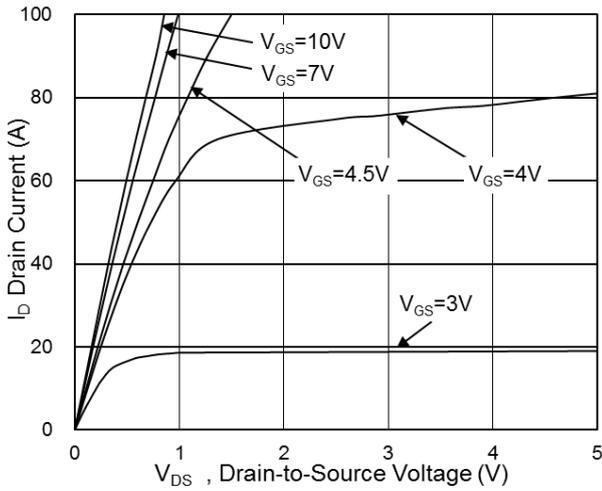
**Drain-Source Diode Characteristics**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current <sup>1,5</sup>	$I_S$	$V_G=V_D=0V$ , Force Current	---	---	34	A
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	$V_{GS}=0V, I_S=1A, T_J=25^{\circ}\text{C}$	---	---	1.2	V
Reverse Recovery Time	$t_{rr}$	$I_F=20A, di/dt=100A/\mu s, T_J=25^{\circ}\text{C}$	---	45	---	nS
Reverse Recovery Charge	$Q_{rr}$		---	165	---	nC

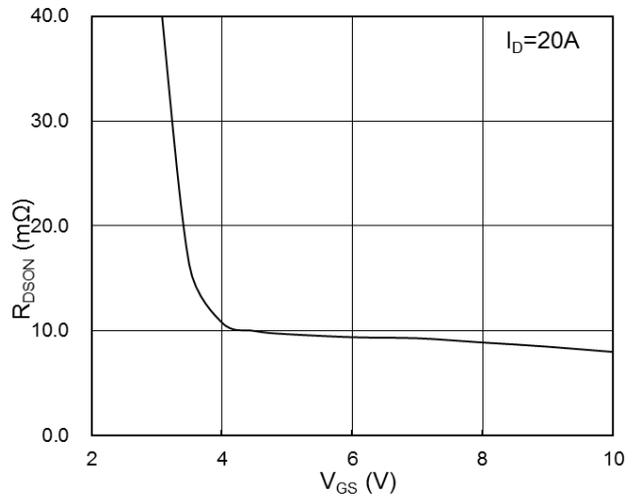
**Note:**

- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
- The EAS data shows Max. rating. The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.3mH, I_{AS}=15A$
- The power dissipation is limited by 150 $^{\circ}\text{C}$  junction temperature
- The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

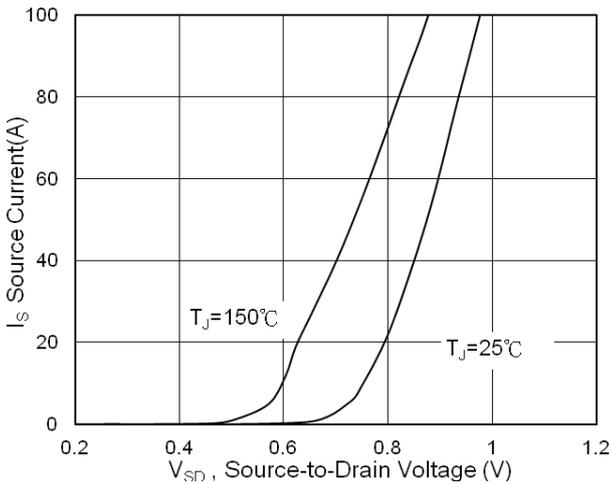
**Typical Characteristics**



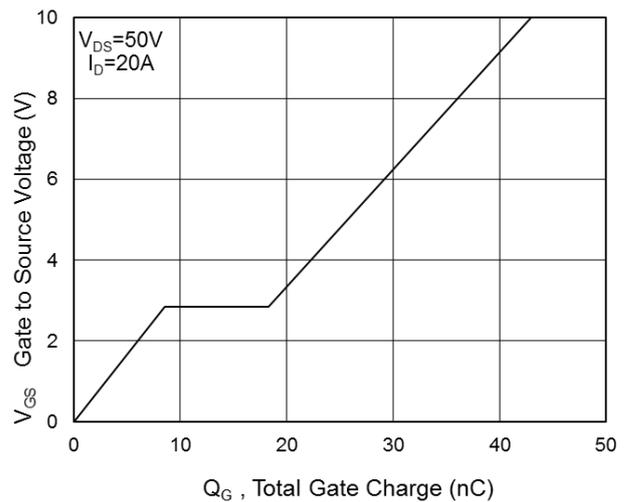
**Fig.1 Typical Output Characteristics**



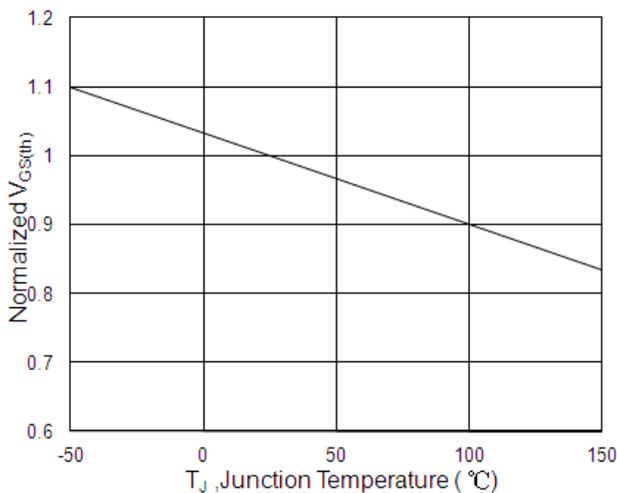
**Fig.2 On-Resistance vs. G-S Voltage**



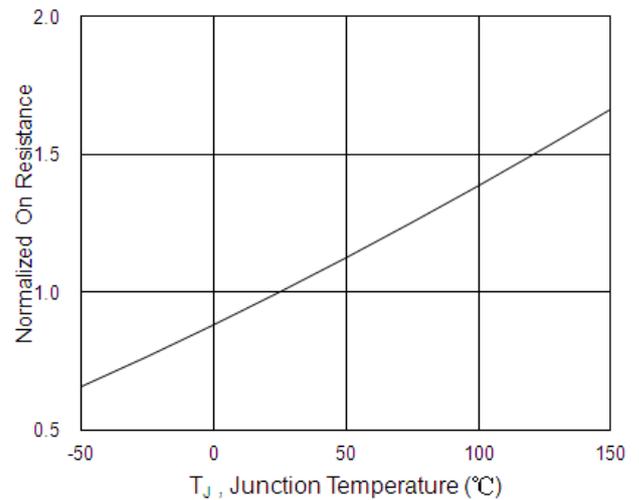
**Fig.3 Source Drain Forward Characteristics**



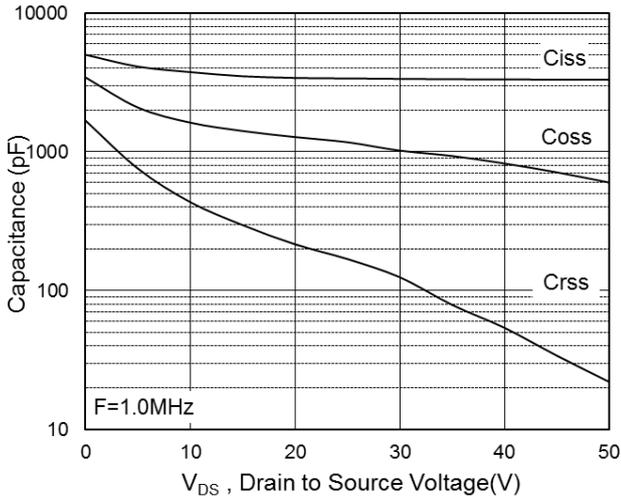
**Fig.4 Gate-Charge Characteristics**



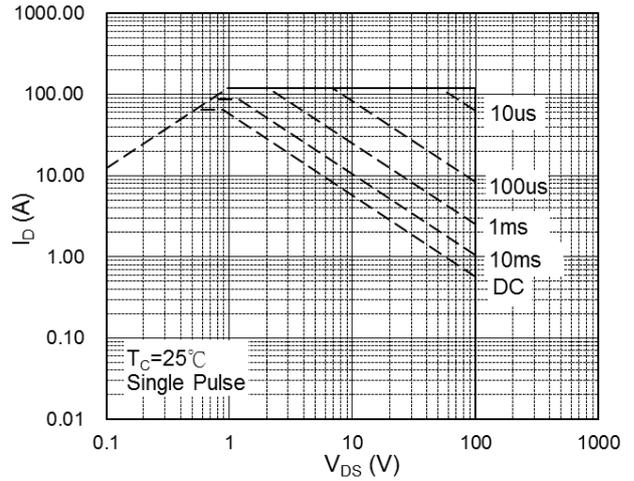
**Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>**



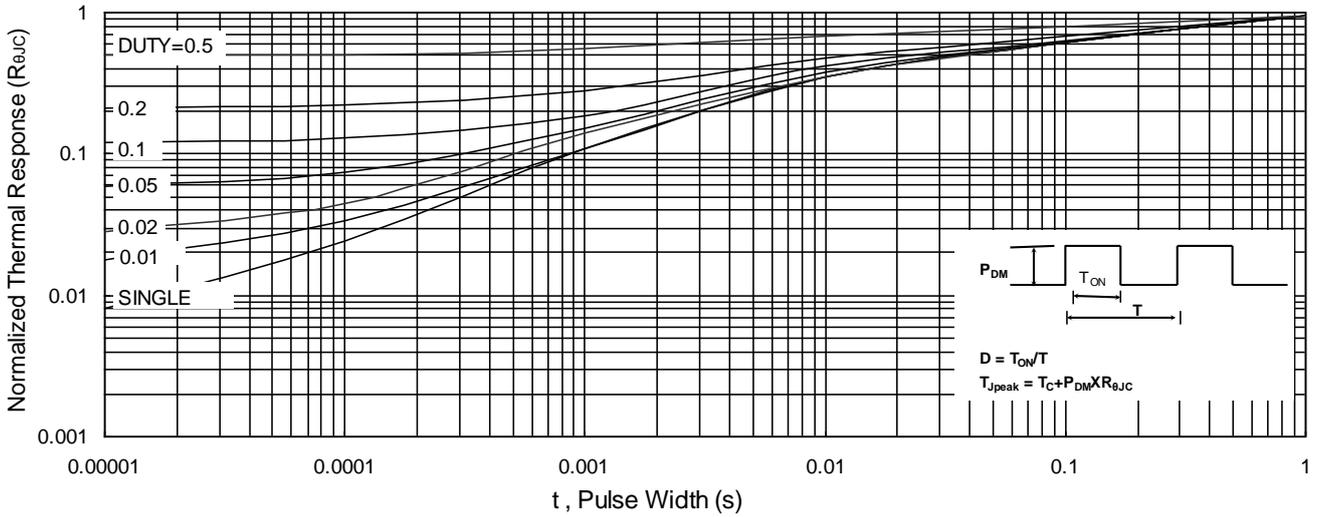
**Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>**



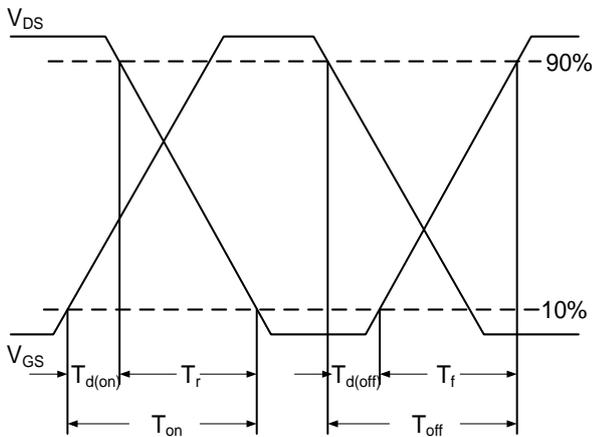
**Fig.7 Capacitance**



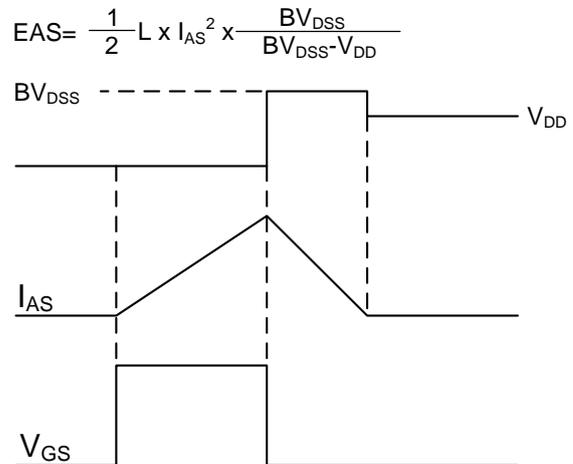
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

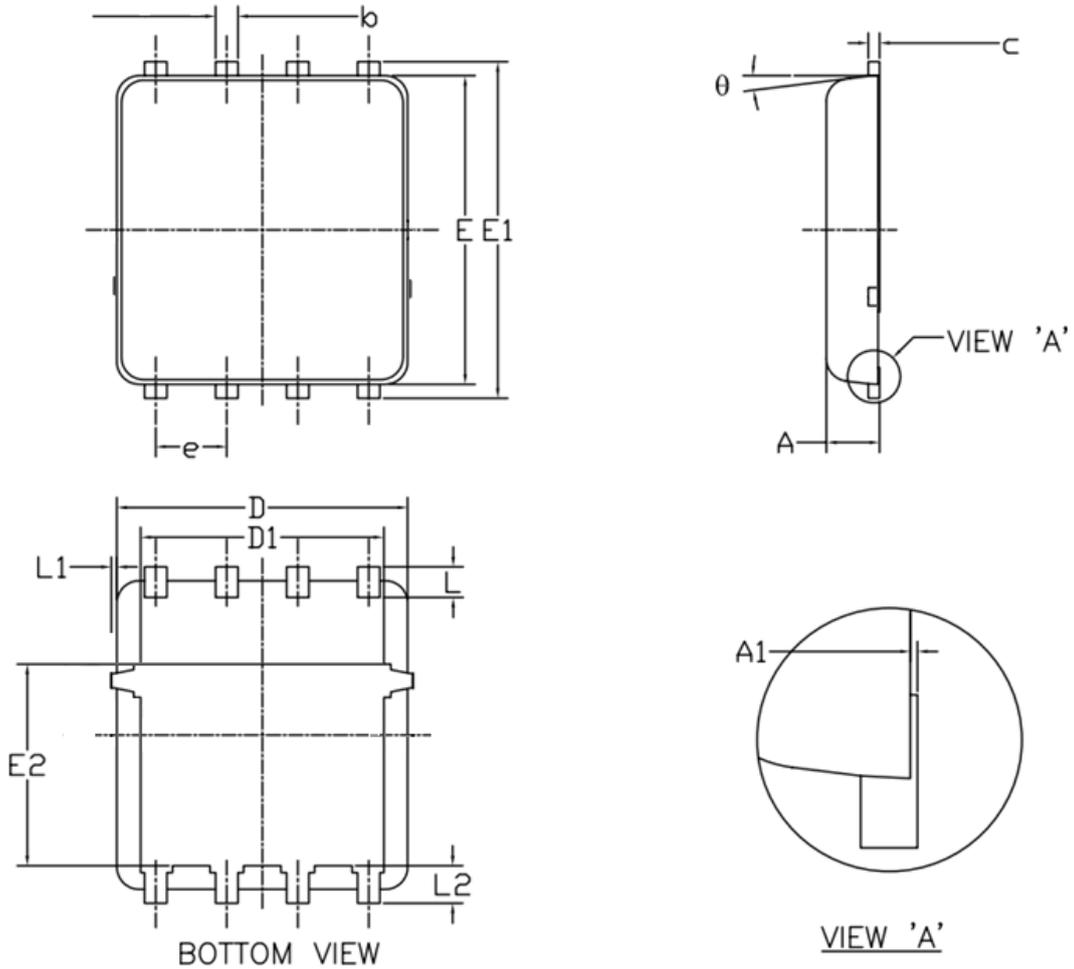


**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**

**DFN5X6-8L Package Outline Dimensions**



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
<b>A</b>	0.90	1.00	1.20	<b>E1</b>	5.90	6.10	6.35
<b>A1</b>	0.00	--	0.05	<b>E2</b>	3.38	3.58	3.92
<b>b</b>	0.30	0.40	0.51	<b>e</b>	1.27 BSC		
<b>c</b>	0.20	0.25	0.33	<b>L</b>	0.51	0.61	0.71
<b>D</b>	4.80	4.90	5.40	<b>L1</b>	--	--	0.15
<b>D1</b>	3.61	4.00	4.25	<b>L2</b>	0.41	0.51	0.61
<b>E</b>	5.65	5.80	6.06	<b>θ</b>	0°	--	12°